

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ADG/23/14311
1.3 Title of PCN	MOSFETs housed in TO-220: Discontinuation of ST Back End Production Line and Transfer to TFME (Assy and Final Test)
1.4 Product Category	see list
1.5 Issue date	2023-10-03

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Mario ASTUTI
2.2.2 Marketing Manager	Anna RANIOLO, Martina GIUFFRIDA
2.2.3 Quality Manager	Diego Maria FERRARI

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Subcon TFME Nantong Fujitsu - China, receiving Plant

### 4. Description of change

	Old	New
4.1 Description	Assembly and Final Test in ST Shenzhen - China	Assembly and Final Test in TFME Nantong Fujitsu - China
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No Impact	

### 5. Reason / motivation for change

5.1 Motivation	Service Continuity - Discontinuation of Back-End production line at ST SHENZHEN plant	
5.2 Customer Benefit	SERVICE CONTINUITY	

### 6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes	
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### 7. Timing / schedule

7.1 Date of qualification results	2023-09-22
7.2 Intended start of delivery	2024-01-01
7.3 Qualification sample available?	Upon Request

### 8. Qualification / Validation

8.1 Description	14311 Validaton report RERLVIP23039_1.0.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-10-03

### 9. Attachments (additional documentations)

14311 Public product.pdf 14311 Details.pdf 14311 Validaton report RERLVIP23039_1.0.pdf
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10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STF100N10F7	
	STF100N6F7	
	STF140N6F7	
	STF19NF20	
	STF20NF20	
	STF40NF20	
STP60NF06FP	STP60NF06FP	

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### Qualification of the change

According to ZVEI Guidelines.

See below details and qualification report included to this Notification



life.augmented

**Discontinuation of Back-End production line at ST SHENZHEN plant for all Mosfet products in TO220 Full Plastic (FP package code).**

**Assembly and Final Test Transfer to TFME subcontractor plant**

# Agenda

3 Change Description

4 ZVEI Guidelines

5 Product lines impacted

6 Conclusions

# Change description

- Aim of this document is to describe the activity performed to qualify the MOSFET products assembled in TO220 Full Plastic (FP package code) in the TFME subcontractor plant, where some of the MOSFET products of the LViP Division are already in production.
- This report shows the qualification activity done to ensure the same quality and electrical characteristics the MOSFET products of the LViP Division assembled in TO220 Full Plastic (FP package code), currently assembled in SHENZHEN plant.
- All reliability tests have been completed with positive results.

# ZVEI Guidelines

- According to ZVEI recommendations, the notification is required.

ID	Type of change	Assessment of impact on Supply Chain regarding following aspects		Remaining risks within Supply Chain?	Understanding of semiconductors experts	Examples to explain
		No	Yes			
	ANY					
	DATA SHEET					
	DESIGN					
	PROCESS - WAFER PRODUCTION					
	BARE DIE					
	PROCESS - ASSEMBLY					
X	SEM-PA-18	Move all or parts of production to a different assembly site.	P	P	Assembly transfer or relocation. Includes transfer as well as additional site.	e.g. dual source / fab strategy
	PACKING/SHIPPING					
	EQUIPMENT					
	TEST FLOW					
X	SEM-TF-01	Move of all or part of electrical wafer test and/or final test to a different test site.	P	P	Tester transfer or relocation. Check impact on SEM-AN-01 Includes transfer as well as additional site.	Dual source strategy

# Mosfet Product lines impacted

## MOSFET Products lines in TO220 (FP package code)

- Commercial Product: STF40NF20 (Silicon Line MM2K01) → Test Vehicle
- Commercial Product : STF100N10F7 (Silicon Line OD0F01) → Test Vehicle
- Commercial Product : STF140N6F7 (Silicon Line OD6E01) → Test Vehicle
- Commercial Product : STP60NF06FP (Silicon Line ED6F01)
- Commercial Product : STF19NF20 (Silicon Line MM2E01)
- Commercial Product : STF20NF20 (Silicon Line MM2G01)
- Commercial Product : STF100N6F7 (Silicon Line OD6401)

# Conclusions

- Detailed qualification activity has been performed in order to qualify the MOSFET products assembled in TO220 Full Plastic (FP package code) in the TFME subcontractor plant. All reliability tests have been completed with positive results.
- This report shows the positive results achieved, ensuring the same quality and electrical characteristics as the current production in Shenzhen ST plant.

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## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** MOSFETs housed in TO-220: Discontinuation of ST Back End Production Line and Transfer to TFME (Assy and Final Test)

**PCN Reference :** ADG/23/14311

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STF40NF20	STF19NF20	STF140N6F7
STF100N6F7	STF100N10F7	STP60NF06FP
STF20NF20		

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